



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: I-0711-01 Product Affected: 89HPES8T5 - BGA Packages Date Effective: March 21, 2008	DATE: December 21, 2007	MEANS OF DISTINGUISHING CHANGED DEVICES: <input checked="" type="checkbox"/> Product Mark Change in Ordering Part Number <input type="checkbox"/> Back Mark <input type="checkbox"/> Date Code <input type="checkbox"/> Other
--	--------------------------------	--

Contact: Bimla Paul Title: Quality Assurance Manager Phone #: (408) 574-6419 Fax #: (408) 284-8362 E-mail: Bimla.Paul@idt.com	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: N/A
---	---

DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology	This notification is to advise our customers that IDT has qualified a new die revision to address the device errata. The details are as follow:
<input type="checkbox"/> Wafer Fabrication Process	Device die revision from Mark Revision "ZH" to Mark Revision "ZB" for 89HPES8T5.
<input type="checkbox"/> Assembly Process	
<input type="checkbox"/> Equipment	
<input type="checkbox"/> Material	There will be a change in ordering part number. Please see attachment for details.
<input type="checkbox"/> Testing	
<input type="checkbox"/> Manufacturing Site	
<input checked="" type="checkbox"/> Data Sheet	There is no change to process and technology.
<input checked="" type="checkbox"/> Other	

RELIABILITY/QUALIFICATION SUMMARY: See attached data. There is no change to the die technology/process.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:
 IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
 IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: I- 0711-01

PCN Type: Die revision

Data Sheet Change Yes

Detail of Change This notification is to advise our customers that IDT has qualified a new die revision to address the device errata. The details are as follow:

Device die revision from Mark Revision "ZH" to Mark Revision "ZB" for 89HPES8T5

There will be a change in ordering part number. Please see Table 1 for details.

The new die revision will address the known errata items as follow:

For 89HPES8T5 Mark Revision "ZH" Errata

1. Eliminate errata item 2a : Hot Reset state does not time out.
2. Eliminate errata item 2b : LSSM- Inadequate TS2 trasmitted in some cases.
3. Eliminate errata item 2c : ASPM link state malfunction.

Table 1

ZH to ZB Transition Parts	
Old Part #	New Part#
89HPES8T5ZHBC	89HPES8T5ZBBC
89HPES8T5ZHBCG	89HPES8T5ZBBCG

Note: For T&R, "T" suffix is added to the part#



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT - PCN #: I-0711-01

Qualification Data

Test Vehicle: IDT89HPES8T5A

Qualification Test Plan and Results:

Test Description	Sample Size/ # Of Fails	Test Results (SS/ # Of Fails)
Dynamic High Temp Operating Life Test	77/0	77/0
* Temperature Cycling (-65 °C to 150 °C, 500 cycle)	45/0	45/0
* Highly Accelerated Stress Test (HAST) (130 °C,85% RH, 100 Hrs)	45/0	45/0
ESD HBM	3/0	3/0
ESD CDM	3/0	3/0

Notes: * Test requires Moisture Pre-Conditioning sequence.